

IN THE ABSTRACT:

Please amend the Abstract as follows:

ABSTRACT OF THE DISCLOSURE

Method for a ~~A~~ low profile multi-IC chip package for high-speed applications comprises a connector for electrically connecting the equivalent outer leads of a set of stacked primary semiconductor packages. In one embodiment, the connector comprises a two-part sheet of flexible insulative polymer with buses formed on one side. In another embodiment, the connector comprises multiple buses formed from conductive polymer. In further embodiments, the primary packages are stacked within a cage and have their outer leads in unattached contact with buses within the cage or, alternatively, are directly fixed to leads or pads on the host circuit board.